



PM0650

High Current, Power Inductors



Description

- Halogen Free
- 125°C maximum total temperature operation
- Surface mount package
- Powder iron core material
- Magnetically shielded, low EMI
- High current carrying capacity, Low core losses
- RoHS compliant

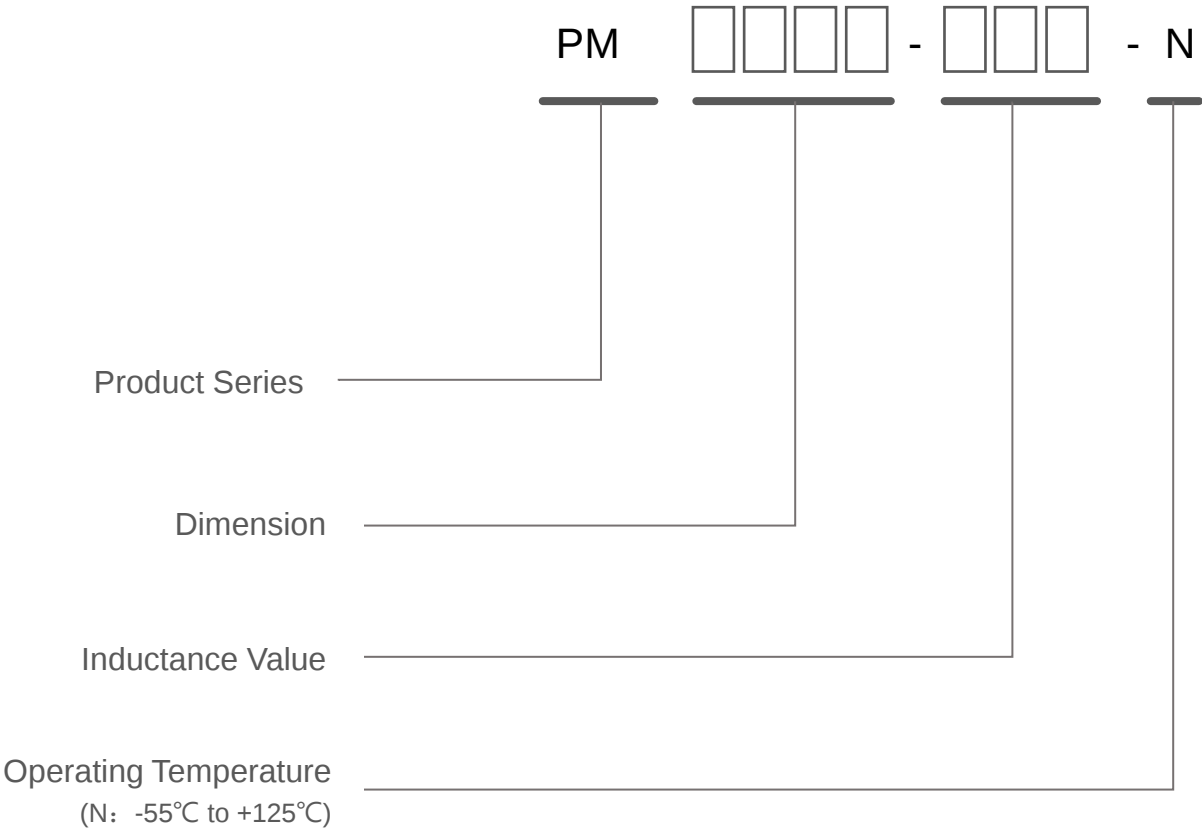
Application

- Voltage Regulator Module (VRM)
- Multi-phase regulators,
- Point-of-load module, Smart phone POL modules
- SSD modules, Notebook regulators
- Battery power systems
- Graphics cards
- Data networking and storage systems
- DC/DC converter
- Cellular phones, LCD displays, HDDs

Environmental Data

- Storage temperature range: -55°C to +125 °C
- Operating temperature range: -40°C to +125°C
(ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant

Ordering Information



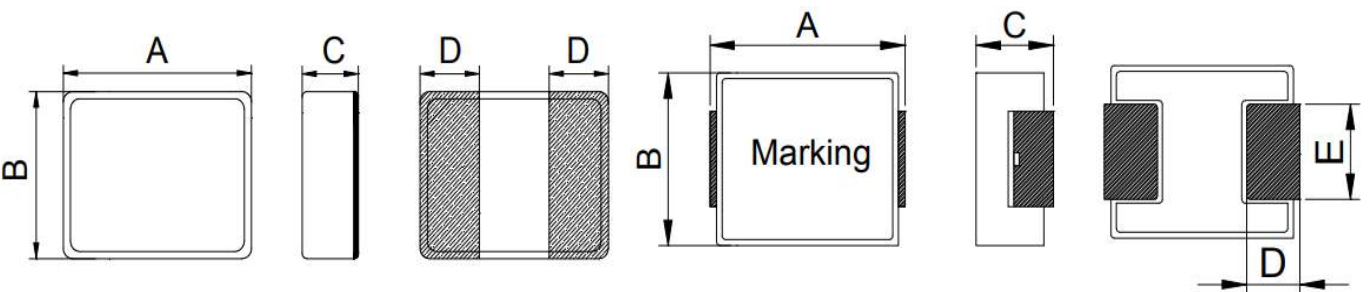
Product Specifications

Part No.	Inductance	DC Resistance		Heating Rating Current	Saturation Current
	L0 (μH)	DCR (mΩ)		Idc (A)	Isat (A)
	± 20 %	TYP.	MAX.	TYP.	TYP.
PM0650-1R0-N	1.0	5.6	6.5	12.0	13.0
PM0650-1R5-N	1.5	7.1	8.5	10.0	12.0
PM0650-2R2-N	2.2	11.6	13.5	7.0	10.0
PM0650-3R3-N	3.3	19.6	22.0	6.5	9.0
PM0650-4R7-N	4.7	27.0	30.0	5.7	8.0
PM0650-6R8-N	6.8	38.0	44.0	5.0	7.0
PM0650-100-N	10	46.0	55.0	4.5	6.0
PM0650-150-N	15	72.0	85.0	3.5	4.0
PM0650-220-N	22	115.0	130.0	2.8	3.2
PM0650-330-N	33	158.0	180.0	2.4	3.0
PM0650-470-N	47	260.0	290.0	2.0	2.5
PM0650-680-N	68	425.0	468.0	1.2	2.0

Notes

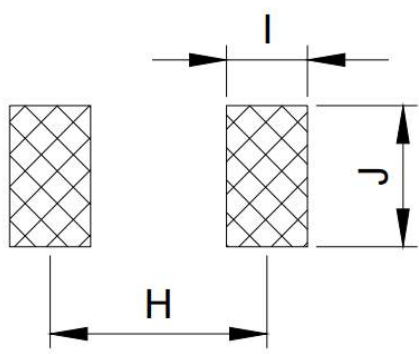
1. Initial Inductance (L0) Test Parameters:1MHz,1V,Idc=0.0A,+25°C
2. Operating temperature range - 40 °C to + 125 °C
3. IDC(A): DC current (A) that will cause an approximate ΔT of 40 °C
4. ISAT(A): DC current (A) that will cause L0 to drop approximately 30 %
5. The part temperature (ambient + temp rise) should not exceed 125 °C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
6. The rated current as listed is either the saturation current or the heating current depending on which value is lower.

Dimensions



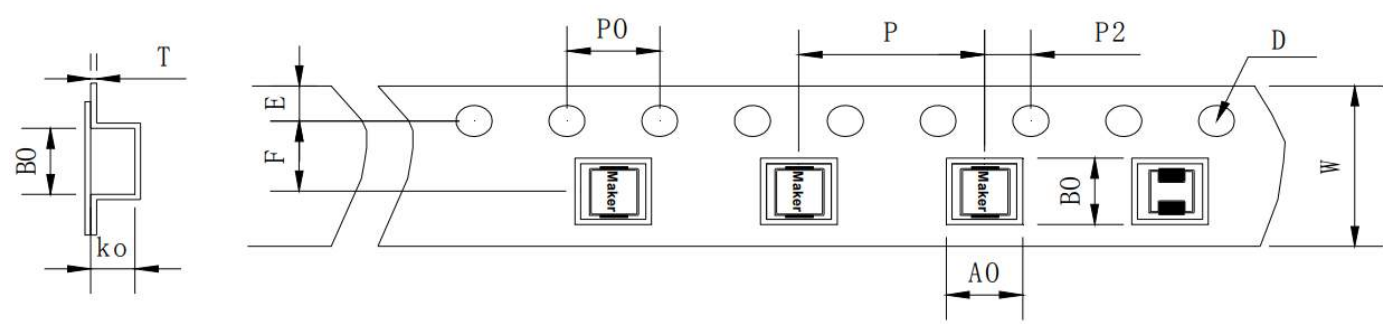
Part No.	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
PM0650-XXX-N	7.5 Max	6.6±0.2	5.0 Max	1.6±0.3	3.0±0.2

RECOMMENDED PCB LAYOUT



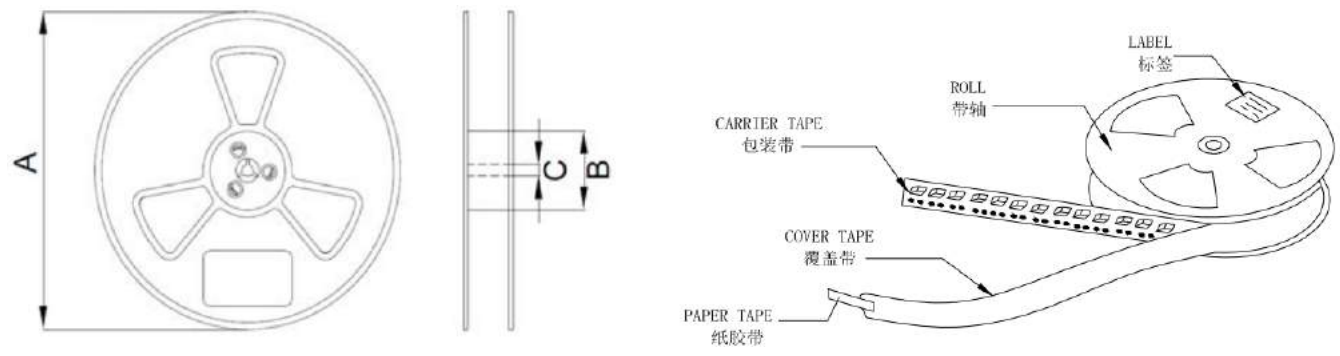
Part No.	H(mm)	I(mm)	J(mm)
PM0650-XXX-N	6.05	2.35	3.5

Tape Dimensions



Part No.	Tape Dimensions(mm)					
	W	A0	B0	K0	D	P0
PM0650-XXX-N	16	7.2	8	5.5	1.5	12

Reel Dimensions



Part No.	Reel Dimensions(mm)		
	A	B	C
PM0650-XXX-N	330	100	13

Numbers of taping

1000 pieces/reel

Reflow Profile

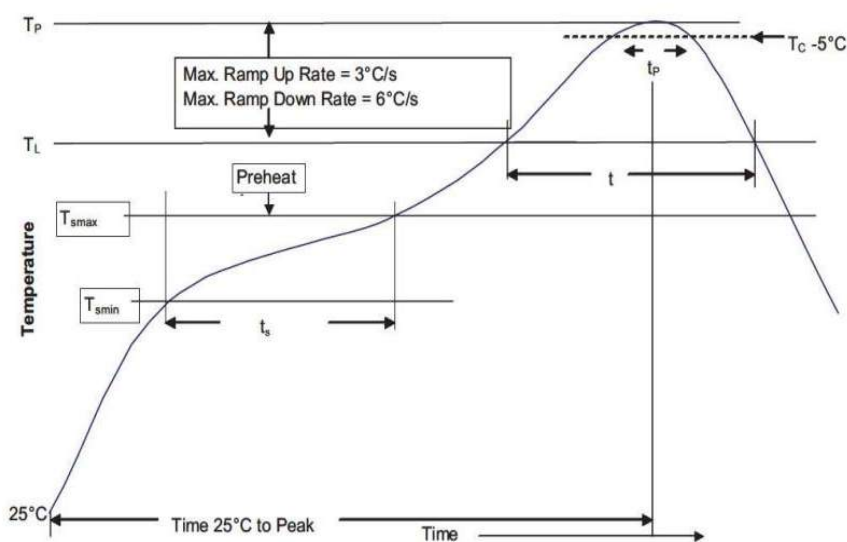


Table 1 - Standard SnPb Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	150°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.



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